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Rev. 10/93

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN THE APPLICATION OF:

MICHAEL ROBERT SAMUELS ET. AL.

CASE NO.: AD6819USDIV

APPLICATION NO.: 10/736928

GROUP ART UNIT: 1775

FILED: DECEMBER 15, 2003

EXAMINER:

FOR: SOLID SHEET MATERIAL ESPECIALLY USEFUL FOR CIRCUIT BOARDS

**REQUEST FOR CORRECTED FILING RECEIPT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The filing receipt for the above-referenced application, a copy of which is attached, incorrectly shows the Domestic Priority data as follows: "This application is a Div. of 10/227,997 08/26/2002". The correct priority for the case is -- This application is a Div. of 10/227,997 08/26/2002, and claims the benefit of 60/315,885, 08/30/2001 --.

Attached is a copy of page 1 of the divisional application, filed December 15, 2003, showing the Cross-Reference to Related Application statement claiming priority to the provisional application.

Accordingly, a corrected filing receipt is requested.

Respectfully submitted,



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Dated: 5-17-05

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## UNITED STATES PATENT AND TRADEMARK OFFICE

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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/736,928	12/15/2003	1775	770	AD6819USDIV		5	1

CONFIRMATION NO. 5332

## FILING RECEIPT

\*OC000000012260672\*

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E I DU PONT DE NEMOURS AND COMPANY  
LEGAL PATENT RECORDS CENTER  
BARLEY MILL PLAZA 25/1128  
4417 LANCASTER PIKE  
WILMINGTON, DE 19805

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Date Mailed: 04/02/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

Michael R. Samuels, Residence Not Provided;  
Subhotosh Khan, Residence Not Provided;  
Mikhail R. Levit, Residence Not Provided;

## Domestic Priority data as claimed by applicant

This application is a DIV of 10/227,997 08/26/2002

## Foreign Applications

If Required, Foreign Filing License Granted: 04/01/2004

Projected Publication Date: 07/08/2004

Non-Publication Request: No

Early Publication Request: No

**PLEASE RECORD ASSIGNMENT  
IN USPTO IF NOT YET RECORDED**

## Title

Solid sheet material especially useful for circuit boards

AD 6819 US DIV

TITLE

SOLID SHEET MATERIAL ESPECIALLY USEFUL FOR CIRCUIT BOARDS

CROSS-REFERENCE TO RELATED APPLICATION

5 This application is a division of co-pending application No. 10/227,997, filed August 26, 2002 and claims the benefit of U.S. Provisional Application No. 60/315,890, filed August 30, 2001.

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FIELD OF INVENTION

The field of invention relates to solid sheets comprising thermoplastic polymer having low moisture absorption and high tensile modulus fibers, in which the thermoplastic polymer is the matrix polymer, substrates for circuit boards made therefrom, and methods of making the foregoing.

BACKGROUND

Circuit boards are important items of commerce, being used in virtually every electronic device. The "board" or supporting member of a circuit board or other electronic devices (such as the interposer in a flip-chip package) is an important component of such devices, and properties of the materials used to make such boards are important to the functioning of the electronic or electrical circuit.

As electronic components have become more sophisticated, the demands placed upon the materials used for boards have increased. For example, for many applications it is preferred that the board have a coefficient of expansion which matches those of the chips mounted on the board, and/or that the board have a low dielectric constant, and low dissipation factor, especially when high frequency devices are mounted on the board. These three factors are often adversely affected